

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3250226

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YUN-YUE LIN	04/23/2012
TA-CHENG LIEN	04/27/2012
HSIN-CHANG LEE	04/23/2012
ANTHONY YEN	04/23/2012
CHIA-JEN CHEN	04/23/2012
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14637189
CORRESPONDENCE DATA	
Fax Number:	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	9727398635
Email:	paula.cunningham@haynesboone.com
Correspondent Name:	HAYNES AND BOONE LLP
Address Line 1:	2323 VICTORY AVENUE
Address Line 2:	SUITE 700
Address Line 4:	DALLAS, TEXAS 75219
ATTORNEY DOCKET NUMBER:	24061.2059US2/2011136901
NAME OF SUBMITTER:	DAVID M. O'DELL
SIGNATURE:	/David M. O'Dell/
DATE SIGNED:	03/04/2015

Total Attachments: 3

source=Executed assignment#page1.tif

source=Executed assignment#page2.tif

source=Executed assignment#page3.tif

Docket No.: 2011-1369 / 24061.2059
 Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- (1) Yun-Yue Lin of No. 388, Jinshui Street, Xiangshan District
Hsinchu City 300, Taiwan R.O.C.
- (2) Ta-Cheng Lien of No. 187, Wunchang Street
Cyonglin Township, Hsinchu County 307
Taiwan R.O.C.
- (3) Hsin-Chang Lee of No. 121, Wen-Hua Road, Wen-Shan Li
Hsin-Pu Zhen, Hsin-Chu Xian
- (4) Anthony Yen of 17F, 296-5 Guangming 6th Road, E. Sec. 1
Zhubei City, Hsinchu County, Taiwan 302 R.O.C.
- (5) Chia-Jen Chen of No. 19-3, Sanchong 1st Road
Jhudong Township, Hsinchu County 310
Taiwan R.O.C.

have invented certain improvements in

MASK AND METHOD FOR FORMING THE SAME

for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and
 xx filed on 04/20/2012 and assigned application number 13/451,767; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any

Docket No.: 2011-1369 / 24061.2059
Customer No.: 42717

country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Yun-Yue Lin
Residence Address: No. 388, Jinshui Street, Xiangshan District
Hsinchu City 300, Taiwan R.O.C.

Dated: 2012. 4. 23.

Yun Yue Lin
Inventor Signature

Inventor Name: Ta-Cheng Lien
Residence Address: No. 187, Wunchang Street
Cyonglin Township, Hsinchu County 307 Taiwan R.O.C.

Dated: 2012. 4. 27

Ta Cheng Lien
Inventor Signature

Inventor Name: Hsin-Chang Lee
Residence Address: No. 121, Wen-Hua Road, Wen-Shan Li
Hsin-Pu Zhen, Hsin-Chu Xian

Dated: 2012. 4. 23

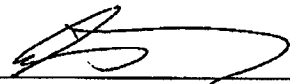
Hsin - Chang Lee
Inventor Signature

Docket No.: 2011-1369 / 24061.2059
Customer No.: 42717

Inventor Name: Anthony Yen

Residence Address: 17F, 296-5 Guangming 6th Road, E. Sec. 1
Zhubei City, Hsinchu County, Taiwan 302 R.O.C.

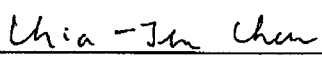
Dated: 4/23/2012


Inventor Signature

Inventor Name: Chia-Jen Chen

Residence Address: No. 19-3, Sanchong 1st Road
Jhudong Township, Hsinchu County 310 Taiwan R.O.C.

Dated: 2012.4.23


Inventor Signature